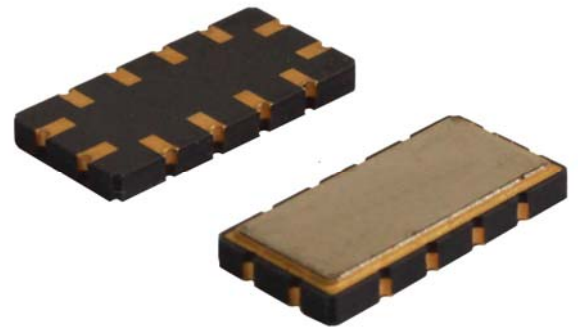


Application

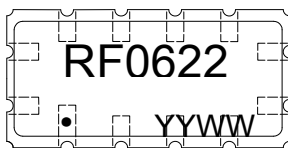
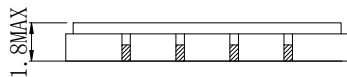
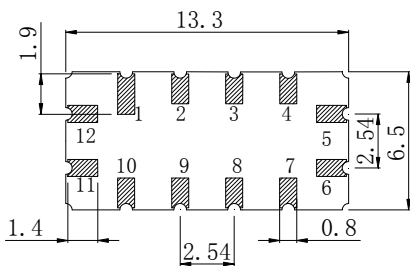
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 0.015 MHz



Features

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 13.30x6.50x1.80mm³
- Package Code QCC12
- **Electrostatic Sensitive Device(ESD)**

Package Dimensions (Unit: mm)



Pin Configuration

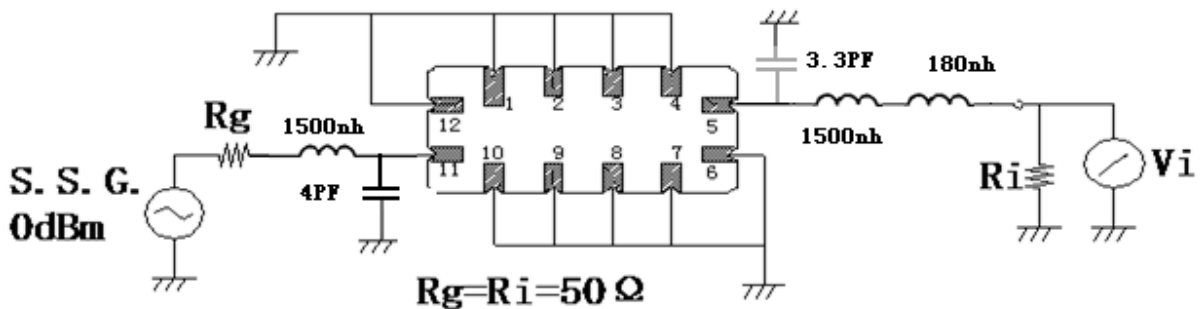
Pin No.	Description
11	Input
5	Output
1,2,3,4,7,8,9,10	Case Ground
6,12	To be Grounded

Marking Description

RF	R	Manufacturer
	F	SAW Filter
0622	Part Number	
●	Pin 1	
YYWW	Year Code & Week Code	

*Fig: If the products produced in 06th week of 2015, The year code & week code is 1506.

Test Circuit (Bottom View)



Performance**Maximum Rating**

Item		Value	Unit
DC Voltage	V _{DC}	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T _{stg}	-55 ~ +125	°C
RF Power Dissipation	P	15	dBm

Electronic Characteristics

Test Temperature: 25°C ± 2°C

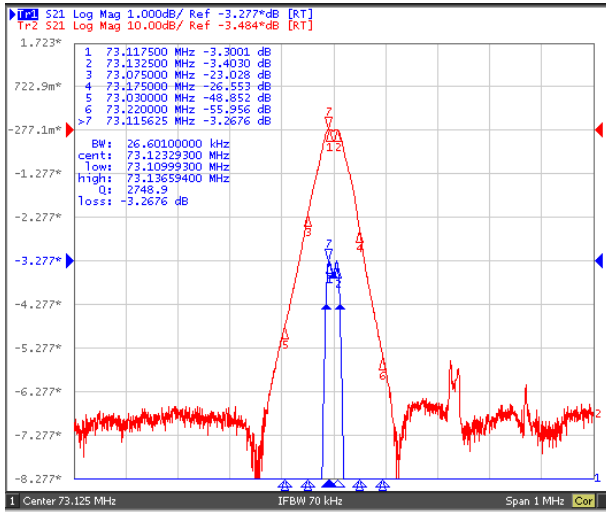
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

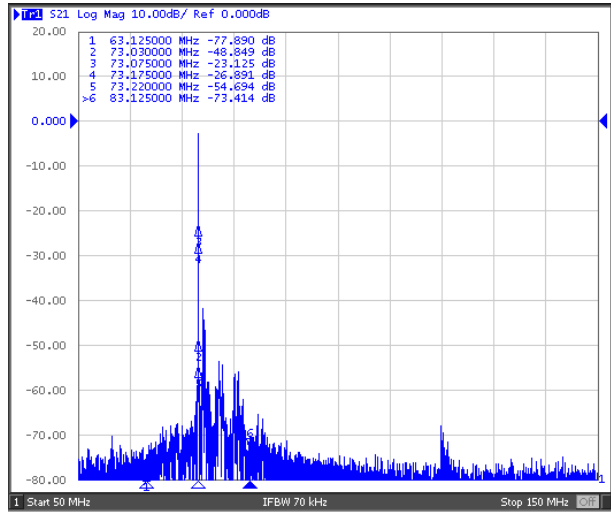
Item		Minimum	Typical	Maximum	Unit
Center Frequency	fc		73.125		MHz
Insertion Loss(min)	IL		3.5	5.5	dB
-30~+85°C					
Insertion Loss(min)	Δα		3.3	5.0	dB
-10~+65°C					
Amplitude Ripple (p-p)	GDR		0.3	0.6	dB
73.1175-73.1325 MHz					
Group Delay Ripple	AD		5.0	10.0	us
73.1175-73.1325 MHz					
Absolute Delay			16.7	25.0	us
Absolute Attenuation					
63.125-73.030MHz		20.0	40.0		dB
73.030-73.075MHz		10.0	20.0		dB
73.175-73.220MHz		10.0	20.0		dB
73.220-83.125MHz		20.0	40.0		dB

Frequency Characteristics

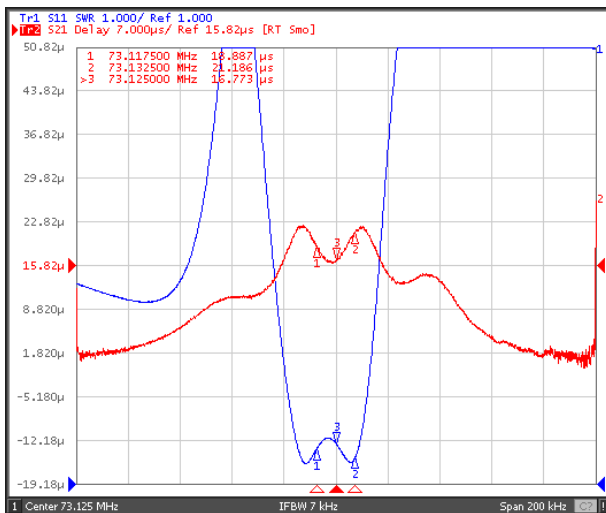
Frequency Response



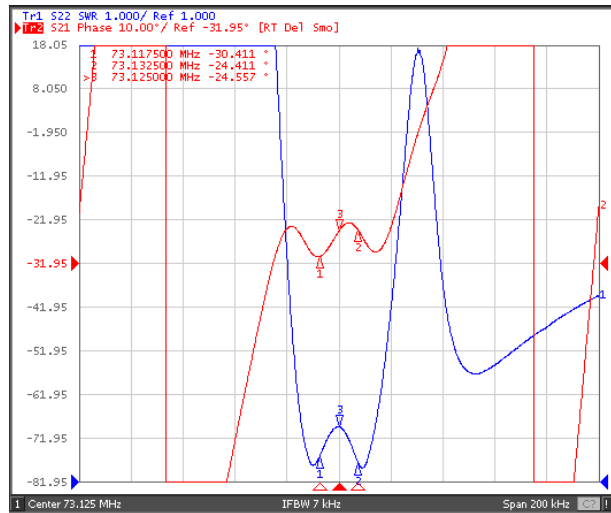
Frequency Response (wideband)



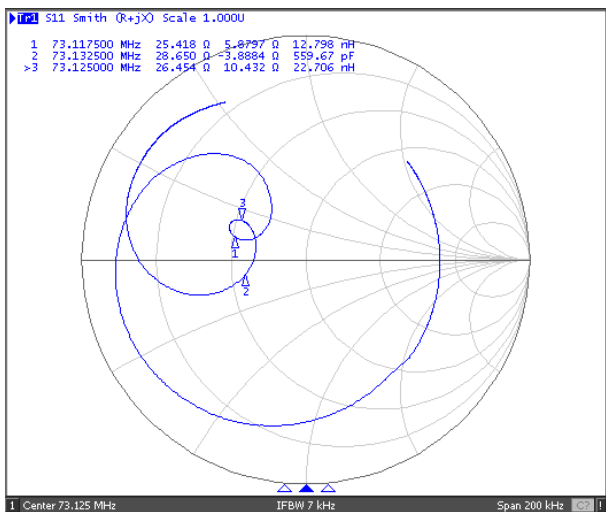
Delay Ripple & S11 VSWR



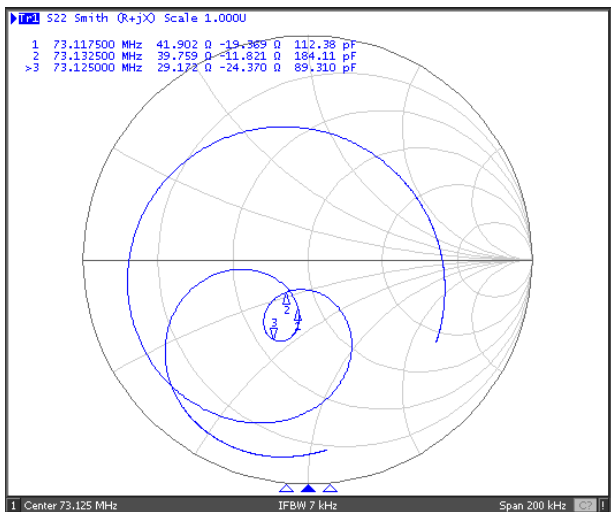
Phase Linearity & S22 VSWR



S11 Smith Chart



S22 Smith Chart



Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.